

ANSI/EIA-364-23C-2006(R2017) Approved: June 21, 2006 Reaffirmed: August 21, 2017

# EIA STANDARD

# **TP-23C**

Low Level Contact Resistance Test Procedure for Electrical Connectors and Sockets

EIA-364-23C (Revision of EIA-364-23B)

June 2006



**Electronic Components Industry Association** 

EIA-364-23C

#### NOTICE

EIA Engineering Standards and Publications are designed to serve the public interest through eliminating misunderstandings between manufacturers and purchasers, facilitating interchangeability and improvement of products, and assisting the purchaser in selecting and obtaining with minimum delay the proper product for his particular need. Existence of such Standards and Publications shall not in any respect preclude any member or nonmember of ECIA from manufacturing or selling products not conforming to such Standards and Publications, nor shall the existence of such Standards and Publications preclude their voluntary use by those other than ECIA members, whether the standard is to be used either domestically or internationally.

Standards and Publications are adopted by ECIA in accordance with the American National Standards Institute (ANSI) patent policy. By such action, ECIA does not assume any liability to any patent owner, nor does it assume any obligation whatever to parties adopting the Standard or Publication.

This EIA Standard is considered to have International Standardization implication, but the International Electrotechnical Commission activity has not progressed to the point where a valid comparison between the EIA Standard and the IEC document can be made.

This Standard does not purport to address all safety problems associated with its use or all applicable regulatory requirements. It is the responsibility of the user of this Standard to establish appropriate safety and health practices and to determine the applicability of regulatory limitations before its use.

(From Standards Proposal No. SP-5393.04 formulated under the cognizance of the CE-2.0 National Connector Standards Committee).

### Published by

©Electronic Components Industry Association 2017 EIA Standards & Technology Department 2214 Rock Hill Road, Suite 265 Herndon, VA 20170

#### **PLEASE !**

# DON'T VIOLATE THE LAW!

This document is copyrighted by the EIA and may not be reproduced without permission.

Organizations may obtain permission to reproduce a limited number of copies through entering into a license agreement. For information, contact:

IHS

15 Inverness Way East Englewood, CO 80112-5704 or call USA and Canada (1-800-854-7179), International (303-397-7956)

# CONTENTS

Clause		Page
1	Introduction	1
1.1 1.2	Scope Object	1 1
2	Test resources	1
2.1 2.2	Equipment Fixture	1 2
3	Test specimen	2
4	Test procedure	2
4.1 4.2 4.3 4.4	Option 1, integrated micro-ohmmeter Option 2, current reversal (direct current) Option 3, offset compensation Option 4, alternating current	3 3 3 3
5	Details to be specified	4
6	Test documentation	4

(This page left blank)

#### TEST PROCEDURE No. 23C

# LOW LEVEL CONTACT RESISTANCE TEST PROCEDURE FOR ELECTRICAL CONNECTORS AND SOCKETS

(From EIA Standards Proposal No. 5105, formulated under the cognizance EIA CE-2.0 Committee on National Connector Standards, and previously published in EIA-364-23B.)

#### 1 Introduction

1.1. Scope

This test procedure may apply to any type or combination of current carrying members such as pin and socket contacts, relay contacts, wire and crimp connectors, or printed circuit board and contact.

#### 1.2. Object

The object of this test procedure is to detail a standard method to measure the electrical resistance of two current carrying members in mutual contact. This test procedure specifies test voltages that will not disturb insulating films on the contacting surface nor cause asperity melting. This procedure addresses the effect of thermal EMF's, a source of measurement error.

#### 2 Test resources

#### 2.1. Equipment

Low level contact resistance measurements may be made using a discrete power source, ammeter and micro-voltmeter or an integrated micro-ohmmeter.

#### 2.1.1. Integrated micro-ohmmeter

Four wire resistance meter that regulates test current, limits open circuit (source) voltage to 20 millivolts maximum, corrects for thermal EMF's, measures voltage drop, such as a Keithley Micro-Ohmmeter model 580, HP 4338B or equivalent, may be used. These meters generally display the measured resistance directly in ohms.

EIA-364-23C Page 2

#### 2.1.2. Discrete Equipment

2.1.2.1. Power source

Power supply or circuit capable of regulating either alternating or direct current within 5% of desired value, and limiting the open circuit (source) voltage to 20 millivolts maximum.

2.1.2.2. Ammeter or current shunt

Capable of measuring either alternating or direct current within an accuracy of 2%.

2.1.2.3. Micro-voltmeter

Capable of measuring either alternating or direct current voltage within an accuracy of 2%

2.1.2.4. Low Level Circuit

Low level circuit delivering 100 milliamperes at 20 millivolts open circuit potential.

2.2. Fixture

The test specimen shall be mated or fixtured as in normal service, or as specified in the referencing document. Fixturing of specimens shall not disturb the natural normal force of the mating contacts.

#### 3 Test specimen

3.1 The test specimen shall be wired as specified in the referencing document. Connections may be made by use of clips, by soldering to a printed circuit board and/or wires. Subsequent measurements should be made at the same point to reduce variability due to path length changes. Soldering the sample to a printed circuit board or to wires fixes the measurement point.

3.2 Voltage probes for crimp contacts shall be placed on the conductors a distance of 152.4 millimeters  $\pm$  3.0 millimeters (6.00 inch  $\pm$  0.12 inch) from each other, with the mated contacts in the center of that distance unless otherwise specified in the referencing document.

#### 4 Test procedure

Measure and record the contact resistance of the specimen under test with a test current of 100 milliamperes maximum and 20 millivolts open circuit (source) voltage maximum. One of the following options shall be used to correct for thermal EMF's.

#### 4.1. Option 1, integrated micro-ohmmeter

Use an 4 wire micro-ohmmeter. The micro-ohmmeter shall employ a method to correct for thermal EMF. Such methods include; alternating current, pulsed direct current or current reversal. Integrated meters generally measure the actual test current and the voltage drop across the specimen. The measured resistance is then internally calculated and displayed.

#### 4.2. Option 2, current reversal (direct current)

Apply direct current through the specimen. Measure the current and record it as  $I_{f}$ . Measure the voltage drop across the specimen and record it as  $V_{f}$ . Reverse the direction of current through the specimen. Do not reverse the voltage leads. Measure the current and record it as  $I_{r}$ . Measure the voltage drop across the specimen and record it as  $V_{r}$ .

Calculate the contact resistance with the following equation:

$$R = \frac{\left|V_{f} - V_{r}\right|}{\left|I_{f}\right| + \left|I_{r}\right|} \tag{1}$$

NOTE — The sign of the voltage readings shall be carried into the equation to obtain a proper result.

#### 4.3. Option 3, offset compensation

Apply direct current through the specimen. Measure the current and record it as I. Measure the voltage drop across the specimen and record it as  $V_1$ .

Remove the current from the specimen. Measure the voltage drop across the specimen as  $V_2$ . Calculate the contact resistance with the following equation:

$$R = \frac{|V_1| - |V_2|}{|I|}$$
(2)

#### 4.4. Option 4, alternating current

Apply alternating current through the specimen. Measure the current and record it as I. Measure the voltage drop across the specimen using a true RMS voltmeter and record it as V.

Calculate the contact resistance with the following equation:

$$R = \frac{|V|}{|I|} \tag{3}$$

EIA-364-23C Page 4

# 5 Details to be specified

The following details shall be specified in the referencing document:

- 5.1 Test specimen preparation or conditioning
- 5.2 Test specimen mating conditions or fixturing
- 5.3 Placement of test leads on specimen (see 3.2)

5.4 Test current and voltage other than 100 milliamperes maximum and 20 millivolts open circuit (source) voltage maximum

5.5 Number of specimens to be tested

#### 6 Test documentation

Documentation shall contain the details specified in clause 5, with any exceptions, and the following:

- 6.1 Title of test
- 6.2 Specimen description
- 6.3 Test specimen preparation or conditioning
- 6.4 Test specimen mating conditions or fixturing
- 6.5 Test equipment used, and date of last and next calibration

6.6 Test current and voltage other than 100 milliamperes maximum and 20 millivolts open circuit (source) voltage maximum

- 6.7 Values and observations
- 6.8 Name of operator and date of test

# **EIA Document Improvement Proposal**

If in the review or use of this document, a potential change is made evident for safety, health or technical reasons, please fill in the appropriate information below and mail or FAX to:

Electronic Components Industry Association				
Engineering Department – Publications Office				
4212 Rock Hill Road, Suite 170				
Herndon, VA 20170-4212				
Phone: (571) 323-0294				

Document No.	Document Title:			
Submitter's Name:	Telephone No.: FAX No.: e-mail:			
Address:				
Urgency of Change:				
Immediate: At next revision:				
Problem Area: a. Clause Number and/or Drawing:				
b. Recommended Changes:				
c. Reason/Rationale for Recommendation:				
Additional Remarks:				
Signature:	Date:			
FOR EIA USE ONLY Responsible Committee:				
Chairman:				
Date comments forwarded to Committee Chairman:				



Electronic Components Industry Association 2214 Rock Hill Road, Suite 265 \* Herndon, VA 20170 \* tel 571-323-0294 \* fax 571-323-0245 www.ecianow.org